ASSOCIATION CONN ELECTRONICS INDU	Material Compos © Copyright 2005. IPC international and Pan-A	, Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declar he declaratior	ration on a contraction of the second	of the substances ompasses all lowe	within the r level mat	manufactur erials for wl	er listed ite hich the ma	em. Note: i inufacture	if the item is an as r has engineering	ssembly with low responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mfg Information				
Supplier Inf	formation														
Company name	e*	Company uni	Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-04			
Contact Name			Title - Contact			]	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*		Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-S	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Req	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date Version Manufactur		ing Site	te Weight* U		UOM	Unit Type		
		1N5407					2024-05-04					1	334.62	mg	Each
lanufactur	ring Proccess Informatio	n						<b>4</b>							
Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 M		J-STD-020 MS	L Rating	Peak Process Body Temperatu		e Max Time at Peak Temper		Temperatu	re Numb	per of Reflow Cyc	cles		
		C	U Alloy						C	30		second	s 3		
omments															
or more infor	mation regarding material co	mposition <sub>l</sub>	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.67	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			Α	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Metal Hydroxide	proprietary data		27.1665	mg
			Supplier	Carbon Black (C)	1333-86-4		5.4333	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.4975	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.333	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		48.8997	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg